

#### **Features**

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- Extremely Fast Switching
- Positive Temperature Coefficient on V<sub>F</sub>

#### **Benefits**

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

## **Applications**

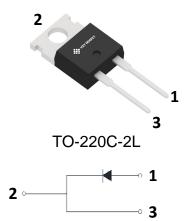
- Switch Mode Power Supplies (SMPS)
- Boost diodes in PFC or DC/DC stages
- Free Wheeling Diodes in Inverter stages
- AC/DC converters

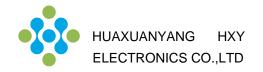




Maximum Ratings (T<sub>c</sub>=25°C unless otherwise specified)

| Symbol                        | Parameter                             | Value          | Unit         | Test Conditions  | Note   |
|-------------------------------|---------------------------------------|----------------|--------------|--|--------|
| V <sub>RRM</sub>              | Repetitive Peak Reverse Voltage       | 1200           | V            |  |        |
| $V_{RSM}$                     | Surge Peak Reverse Voltage            | 1300           | V            |  |        |
| V <sub>R</sub>                | DC Peak Reverse Voltage               | 1200           | V            |  |        |
| $\mathrm{I}_{_{F}}$           | Continuous Forward Current            | 19<br>9.5<br>5 | А            | T <sub>c</sub> =25°C<br>T <sub>c</sub> =135°C<br>T <sub>c</sub> =161°C                 | Fig. 3 |
| $\mathbf{I}_{FRM}$            | Repetitive Peak Forward Surge Current | 26<br>18       | А            | $T_c$ =25°C, $t_p$ =10 ms, Half Sine Pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine Pulse |        |
| $\mathbf{I}_{\text{FSM}}$     | Non-Repetitive Forward Surge Current  | 46<br>36       | А            | $T_c$ =25°C, $t_p$ =10 ms, Half Sine Pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine Pulse | Fig. 8 |
| $\mathrm{I}_{\mathrm{F,Max}}$ | Non-Repetitive Peak Forward Current   | 400<br>320     | А            | $T_c$ =25°C, $t_p$ =10 $\mu$ s, Pulse $T_c$ =110°C, $t_p$ =10 $\mu$ s, Pulse           | Fig. 8 |
| $P_{tot}$                     | Power Dissipation                     | 100<br>43      | W            | T <sub>c</sub> =25°C<br>T <sub>c</sub> =110°C  | Fig. 4 |
| dV/dt                         | Diode dV/dt ruggedness                | 200            | V/ns         | V <sub>R</sub> =0-650V   |        |
| ∫i²dt                         | i²t value                             | 10.6<br>6.5    | A²s          | $T_c$ =25°C, $t_p$ =10 ms<br>$T_c$ =110°C, $t_p$ =10 ms                                |        |
| T,                            | Operating Junction Range              | -55 to<br>+175 | °C           |  |        |
| T <sub>stg</sub>              | Storage Temperature Range             | -55 to<br>+135 | °C           |  |        |
|                               | TO220-2L Mounting Torque              | 1<br>8.8       | Nm<br>lbf-in | M3 Screw<br>6-32 Screw   |        |





## **Electrical Characteristics**

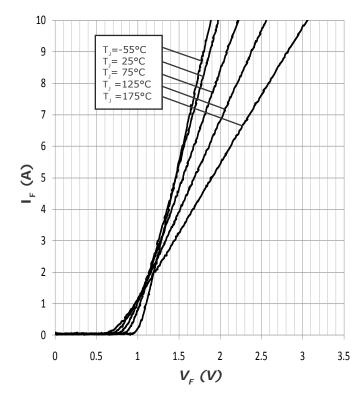
| Symbol         | Parameter                 | Тур.            | Max.       | Unit | Test Conditions  | Note   |
|----------------|---------------------------|-----------------|------------|------|--|--------|
| V <sub>F</sub> | Forward Voltage           | 1.4<br>1.9      | 1.8<br>3   | V    | $I_F = 5 \text{ A } T_J = 25^{\circ}\text{C}$<br>$I_F = 5 \text{ A } T_J = 175^{\circ}\text{C}$  | Fig. 1 |
| I <sub>R</sub> | Reverse Current           | 20<br>40        | 150<br>300 | μA   | $V_R = 1200 \text{ V } T_J = 25^{\circ}\text{C}$<br>$V_R = 1200 \text{ V } T_J = 175^{\circ}\text{C}$  | Fig. 2 |
| Q <sub>c</sub> | Total Capacitive Charge   | 27              |            | nC   | $V_R = 800 \text{ V, } I_F = 5\text{A}$<br>$di/dt = 200 \text{ A/}\mu\text{s}$<br>$T_J = 25^{\circ}\text{C}$   | Fig. 5 |
| С              | Total Capacitance         | 390<br>27<br>20 |            | pF   | $V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$<br>$V_R = 400 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$<br>$V_R = 800 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ | Fig. 6 |
| E <sub>c</sub> | Capacitance Stored Energy | 8.0             |            | μЈ   | V <sub>R</sub> = 800 V   | Fig. 7 |

Note: This is a majority carrier diode, so there is no reverse recovery charge.

## **Thermal Characteristics**

| Sy | ymbol           | Parameter                                | Тур. | Unit | Note   |
|----|-----------------|--|------|------|--------|
|    | $R_{\theta JC}$ | Thermal Resistance from Junction to Case | 1.5  | °C/W | Fig. 9 |

## **Typical Performance**





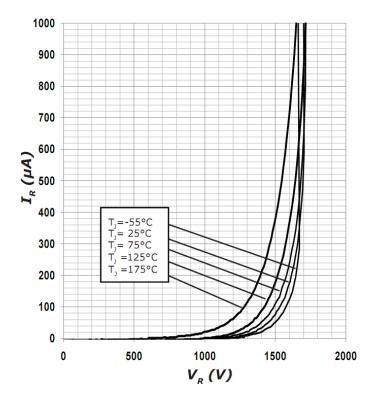
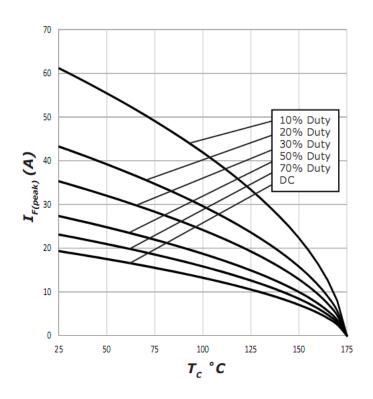


Figure 2. Reverse Characteristics

## **Typical Performance**



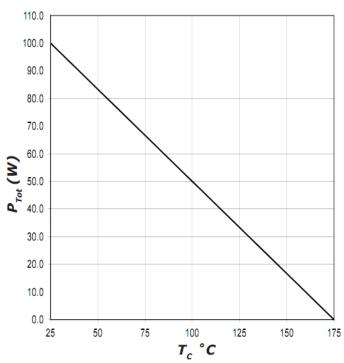


Figure 3. Current Derating

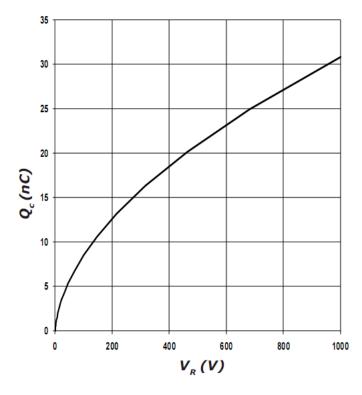


Figure 4. Power Derating

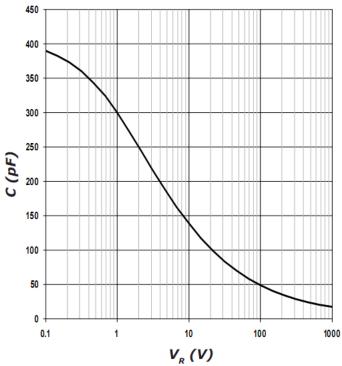


Figure 5. Recovery Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

## **Diode Model**

$$Vf_{T} = V_{T} + If * R_{T}$$

$$V_{T} = 0.96 + (T_{j} * -1.22*10^{-3})$$

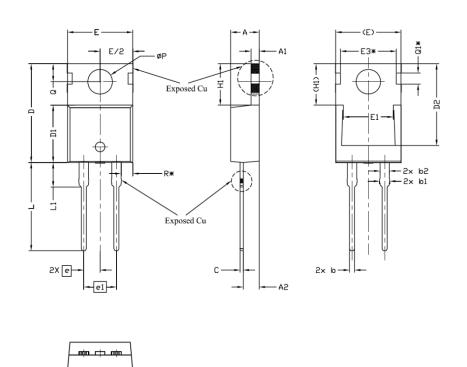
$$R_{T} = 0.08 + (T_{j} * 8.5*10^{-4})$$

$$V_{T} = R_{T}$$

Note: T<sub>i</sub> is diode junction temperature in degrees Celsius

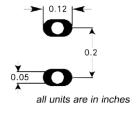


# Package Information TO-220C-2L

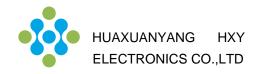


|        | [              |       |       |       |  |
|--------|----------------|-------|-------|-------|--|
| SYMBOL | MIN. NOM. MAX. |       |       | NOTES |  |
| А      | 4,24           | 4.44  | 4,64  |       |  |
| A1     | 1.15           | 1.27  | 1.40  |       |  |
| A2     | 2.30           | 2.48  | 2.70  |       |  |
| þ      | 0.70           | 0.80  | 0.90  |       |  |
| b1     | 1.20           | 1.55  | 1.75  |       |  |
| b2     | 1.20           | 1,45  | 1.70  |       |  |
| С      | 0.40           | 0.50  | 0.60  |       |  |
| D      | 14.70          | 15.37 | 16.00 | 4     |  |
| D1     | 8.82           | 8.92  | 9.02  |       |  |
| D2     | 12.43          | 12.73 | 12.83 | 5     |  |
| E      | 9.96           | 10.16 | 10.36 | 4,5   |  |
| E1     | 6,86           | 7.77  | 8,89  | 5     |  |
| E3*    | E3* 8.70REF.   |       |       |       |  |
| е      | 2,54BSC        |       |       |       |  |
| e1     | 5.08BSC        |       |       |       |  |
| H1     | 6.30           | 6.45  | 6.60  | 5,6   |  |
| L      | 13,47          | 13.72 | 13.97 |       |  |
| L1     | 3.60           | 3.80  | 4.00  |       |  |
| ØP     | 3.75           | 3.84  | 3.93  |       |  |
| Q      | 2,60 2,80      |       | 3,00  |       |  |
| Q1*    |                |       |       |       |  |
| R*     |                |       |       |       |  |

## **Recommended Solder Pad Layout**



TO-220C-2L



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